ABSTRACT OF THE DISCLOSURE

ELECTROLESS COPPER DEPOSITION

A method for providing metal filled features in a layer is provided. A metal seed layer is deposited on tops and bottoms of the features. Metal seed layer on tops of the features and overhangs is removed without removing metal seed layer on bottoms of features. An electroless deposition of metal is provided to fill the features, wherein the electroless deposition first deposits on the metal seed layer on bottoms of the features.

FIG. 1



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